

Memory Packaging Market Forecasts to 2028 – Global Analysis By Platform (Wire-Bond, Flip Chip and Others), Application (TSV Packaging, DRAM Packaging and Others), End User (Automotive, Medical Devices and Others) and By Geography

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Abstracts

According to Statistics MRC, the Global Memory Packaging Market is accounted for \$32.43 billion in 2020 and is expected to reach \$57.84 billion by 2028 growing at a CAGR of 7.5% during the forecast period. Growth in packaging and assembly infrastructure, rising demand for smartphones and growing popularity of autonomous driving are driving the market growth. However, thermal issues due to the miniaturization of memory are hampering the growth of the market.

Memory is made of small semiconductor chips similar to processors and should be packaged into less fragile and tiny chips to be integrated with the rest of the system. There are many different memory device packaging options available, used in a wide range of packaging technologies, depending on product requirements, like performance, density, and cost.

Based on the end user, the automotive segment is going to have lucrative growth during the forecast period owing to increase in acceptance of DRAM memory. Furthermore, the growth is led by the trend of autonomous driving and in vehicle infotainment. By geography, Asia Pacific is going to have high growth during the forecast period which can be attributed to a wide range of applications in several consumer electronics, especially in tablets and smartphones.

Some of the key players profiled in the Memory Packaging Market include Apple Inc., ASE Group, Cisco Systems Inc., Dell EMC, Fujitsu Semiconductor Limited, Hana

Micron Inc., IBM Corporation, Intel Corporation, Micron Technology Inc., Nanya Technology Corporation, Qualcomm Technologies Inc., Samsung Electronics Co. Ltd, SK Hynix Inc., STMicroelectronics and Toshiba Electronic Devices & Storage Corporation.

Platforms Covered:

Wafer-Level Chip-Scale Packaging(WLCSP)

Wire-Bond

Flip-Chip

Lead-Frame

Through-Silicon Via (TSV)

Applications Covered:

3D Through-Silicon Via (TSV) Packaging

Dynamic Random Access Memory (DRAM) Packaging

Not AND (NAND) Flash Packaging

Not OR (NOR) Flash Packaging

End Users Covered:

Automotive

Consumer Electronics

Embedded Systems

Information Technology (IT) & Telecom

Medical Devices

Military and Aerospace

Regions Covered:

North America

US

Canada

Mexico

Europe

Germany

UK

Italy

France

Spain

Rest of Europe

Asia Pacific

Japan

China

India

Australia

New Zealand

South Korea

Rest of Asia Pacific

South America

Argentina

Brazil

Chile

Rest of South America

Middle East & Africa

Saudi Arabia

UAE

Qatar

South Africa

Rest of Middle East & Africa

What our report offers:

Market share assessments for the regional and country-level segments

Strategic recommendations for the new entrants

Covers Market data for the years 2018, 2019, 2020, 2024 and 2027

Market Trends (Drivers, Constraints, Opportunities, Threats, Challenges,
Investment Opportunities, and recommendations)

Strategic recommendations in key business segments based on the market estimations

Competitive landscaping mapping the key common trends

Company profiling with detailed strategies, financials, and recent developments

Supply chain trends mapping the latest technological advancements

Free Customization Offerings:

All the customers of this report will be entitled to receive one of the following free customization options:

Company Profiling

Comprehensive profiling of additional market players (up to 3)

SWOT Analysis of key players (up to 3)

Regional Segmentation

Market estimations, Forecasts and CAGR of any prominent country as per the client's interest (Note: Depends on feasibility check)

Competitive Benchmarking

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